

Device Modeling Report

COMPONENTS: MOSFET (Model Parameters)
PART NUMBER: 2SK2963
MANUFACTURER: TOSHIBA
Body Diode (Model Parameters) / ESD Protection Diode



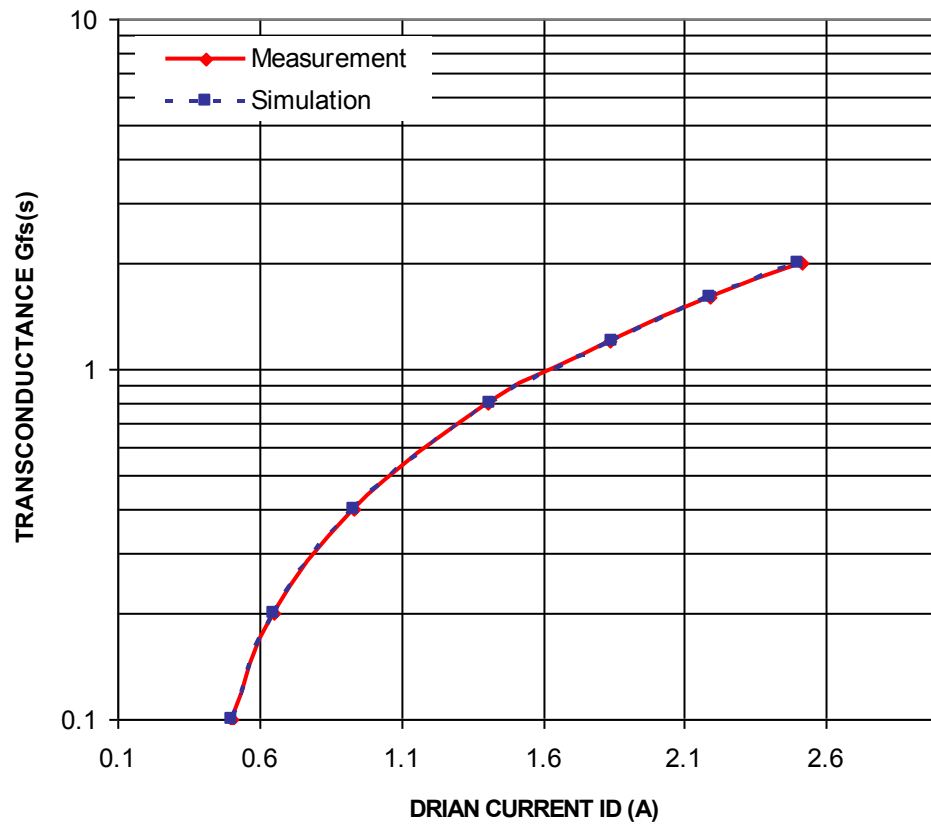
Bee Technologies Inc.

MOSFET MODEL PARAMETERS

PSpice model parameter	Model description
LEVEL	
L	Channel Length
W	Channel Width
KP	Transconductance
RS	Source Ohmic Resistance
RD	Ohmic Drain Resistance
VTO	Zero-bias Threshold Voltage
RDS	Drain-Source Shunt Resistance
TOX	Gate Oxide Thickness
CGSO	Zero-bias Gate-Source Capacitance
CGDO	Zero-bias Gate-Drain Capacitance
CBD	Zero-bias Bulk-Drain Junction Capacitance
MJ	Bulk Junction Grading Coefficient
PB	Bulk Junction Potential
FC	Bulk Junction Forward-bias Capacitance Coefficient
RG	Gate Ohmic Resistance
IS	Bulk Junction Saturation Current
N	Bulk Junction Emission Coefficient
RB	Bulk Series Resistance
PHI	Surface Inversion Potential
GAMMA	Body-effect Parameter
DELTA	Width effect on Threshold Voltage
ETA	Static Feedback on Threshold Voltage
THETA	Mobility Modulation
KAPPA	Saturation Field Factor
VMAX	Maximum Drift Velocity of Carriers
XJ	Metallurgical Junction Depth
UO	Surface Mobility

Transconductance Characteristic

Circuit Simulation Result

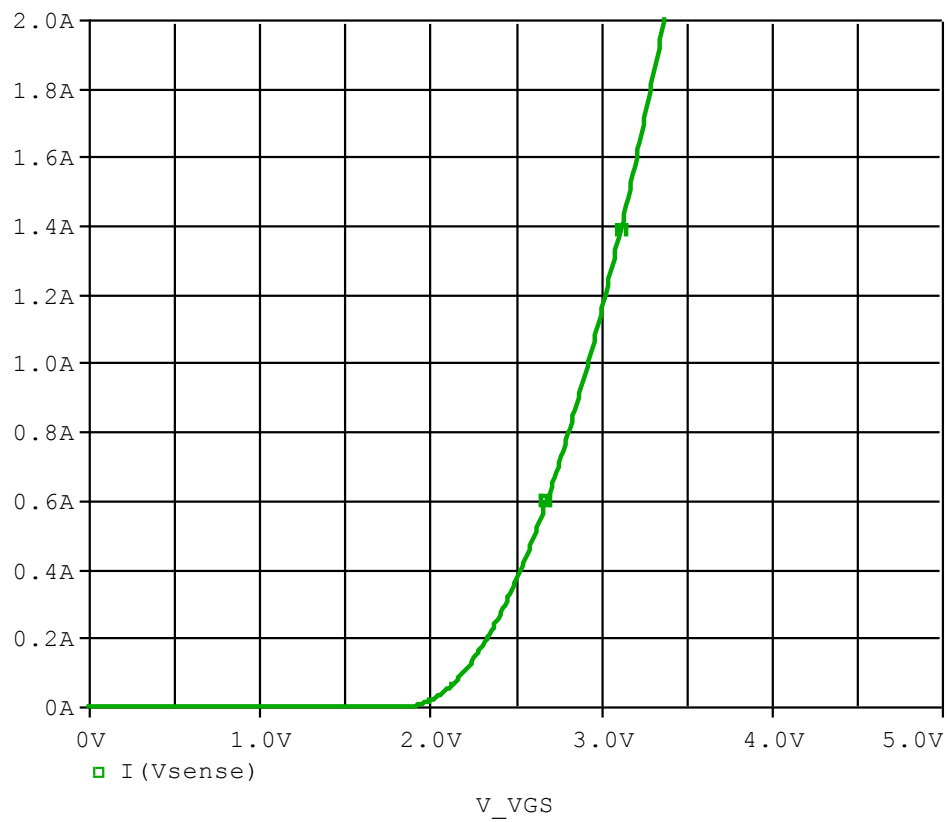


Comparison table

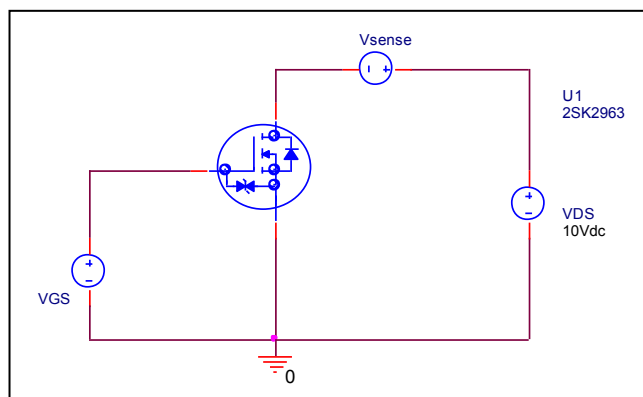
Id(A)	Gfs(S)		Error(%)
	Measurement	Simulation	
0.1	0.5001	0.5000	-0.0240
0.2	0.6500	0.6510	0.1538
0.4	0.9311	0.9302	-0.0942
0.8	1.4056	1.4109	0.3827
1.2	1.8333	1.8440	0.5844
1.6	2.1900	2.1891	-0.0434
2	2.5111	2.5000	-0.4424

Vgs-Id Characteristic

Circuit Simulation result

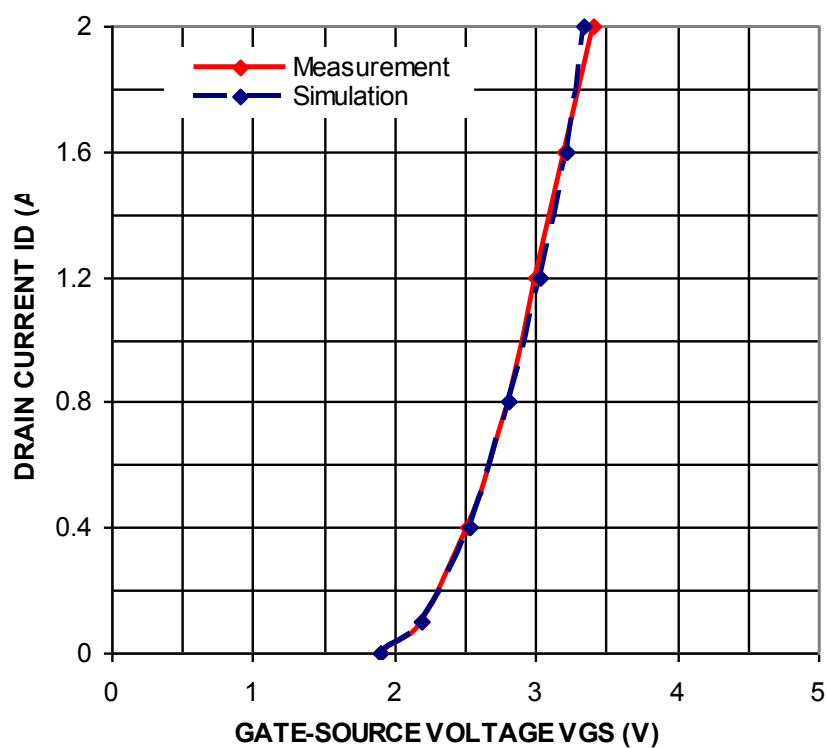


Evaluation circuit



Comparison Graph

Circuit Simulation Result

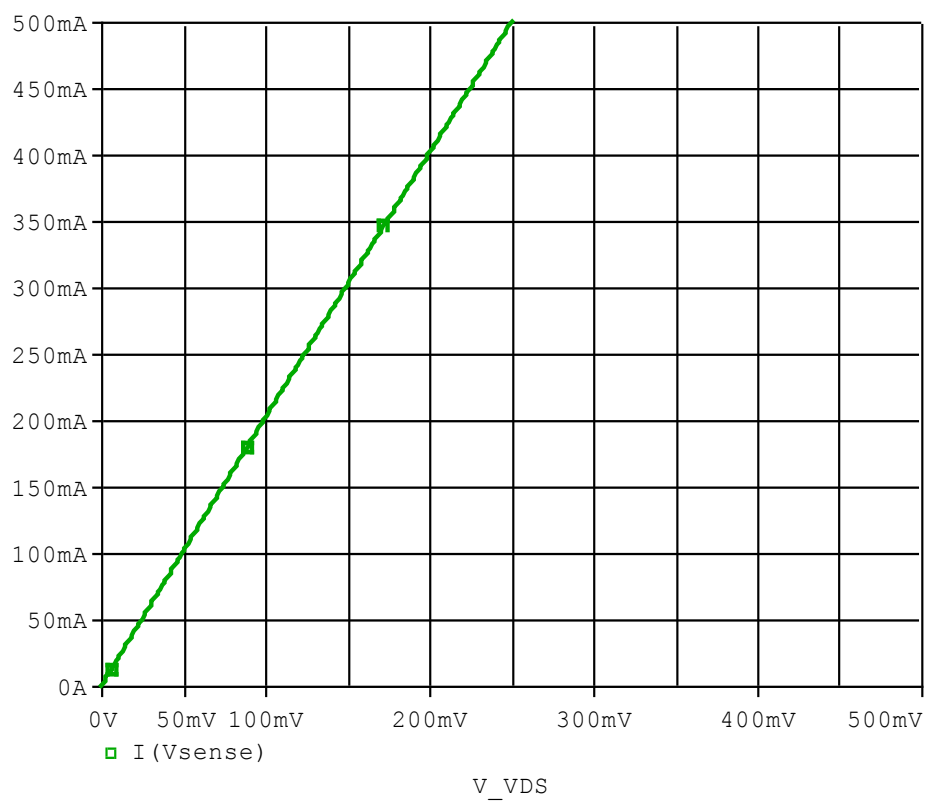


Simulation Result

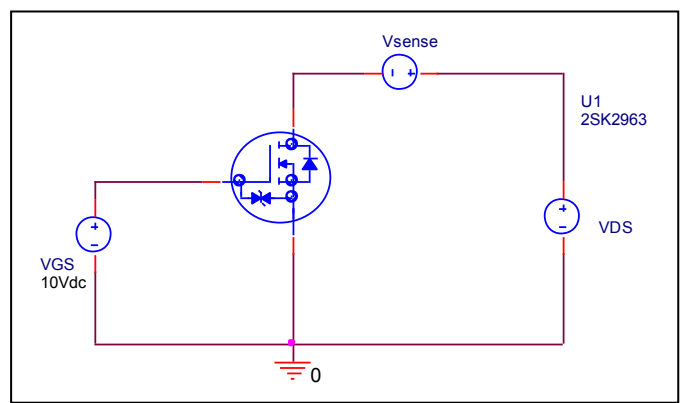
ID(A)	VGS(V)		Error (%)
	Measurement	Simulation	
0.1	2.2000	2.1980	-0.0909
0.4	2.5200	2.5340	0.5556
0.8	2.8000	2.8138	0.4929
1.2	3.0000	3.0295	0.9833
1.6	3.2000	3.2122	0.3813
2	3.4000	3.4278	0.8176

Rds(on) Characteristic

Circuit Simulation result



Evaluation circuit

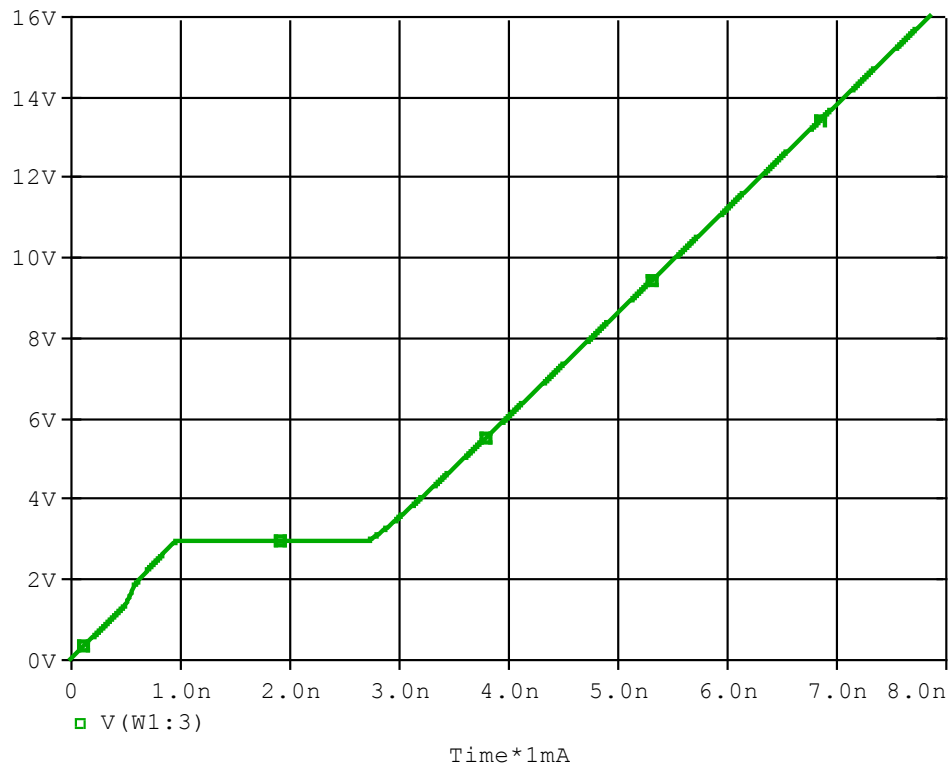


Simulation Result

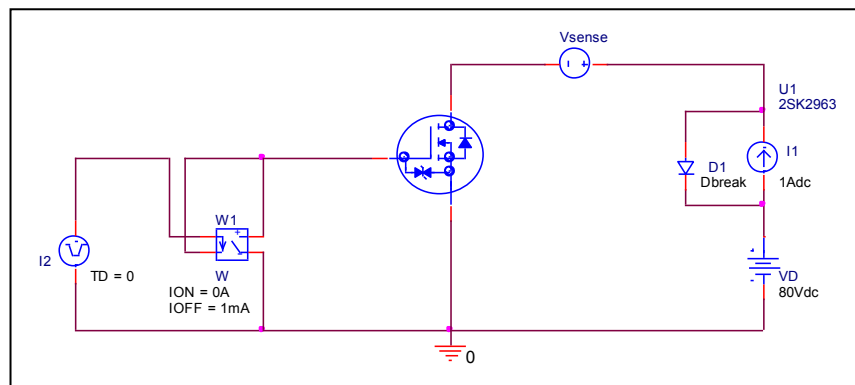
$I_D=0.5A, V_{GS}=10V$	Measurement		Simulation		Error (%)
$R_{DS(on)}$	0.500	Ω	0.5000	Ω	0.000

Gate Charge Characteristic

Circuit Simulation result



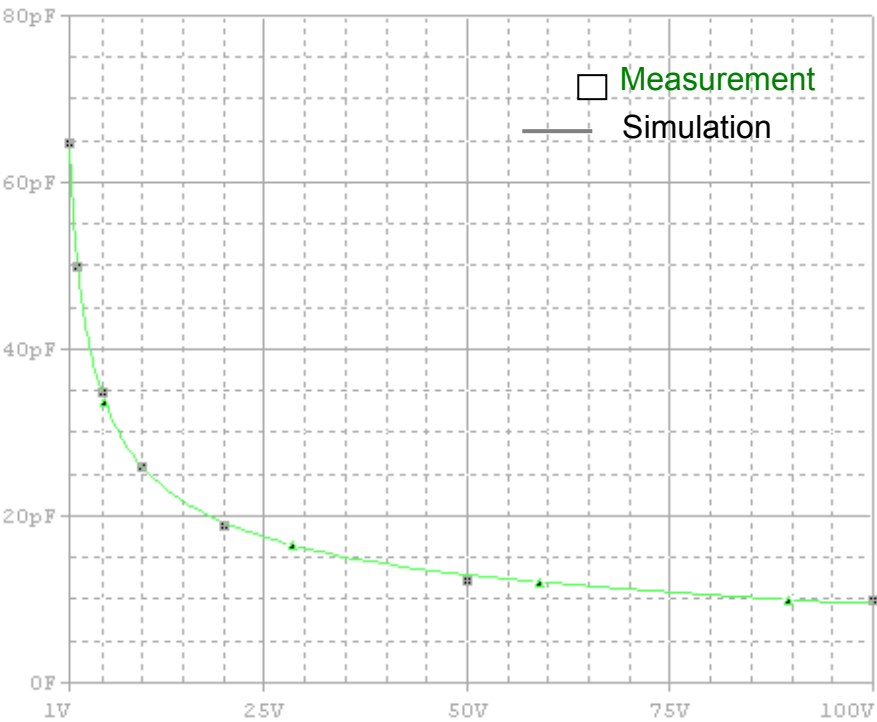
Evaluation circuit



Simulation Result

$V_{DD}=80V$, $I_D=1A$	Measurement		Simulation		Error (%)
Qgs	0.9950	nC	0.9960	nC	0.1005
Qgd	2.8000	nC	2.8010	nC	0.0357

Capacitance Characteristic

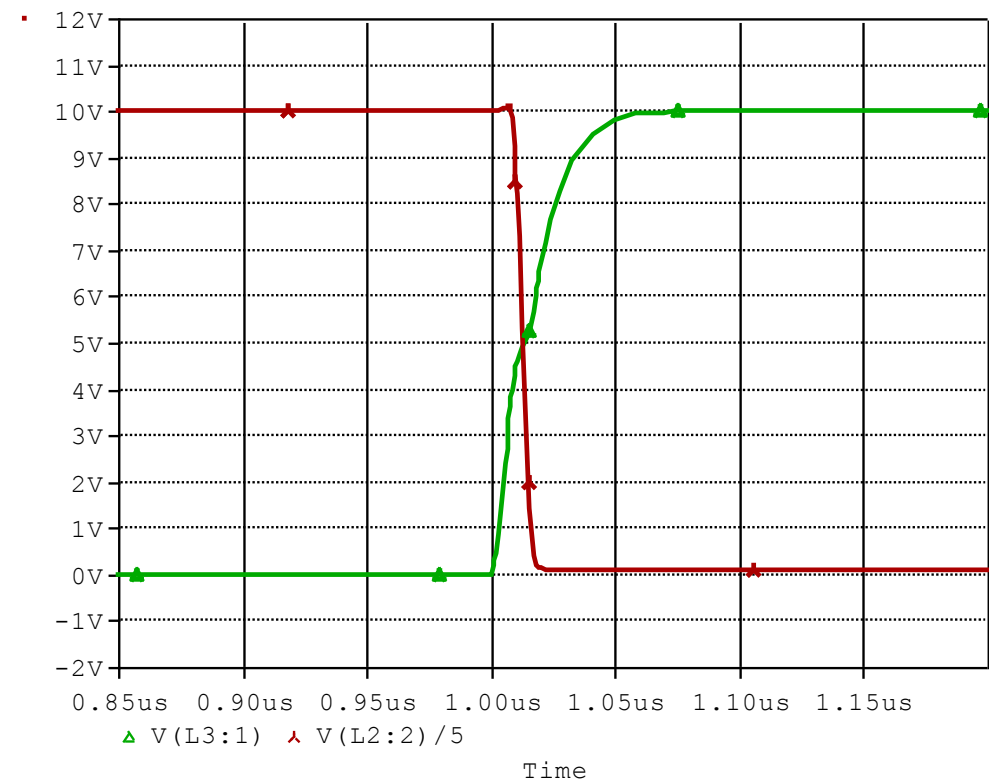


Simulation Result

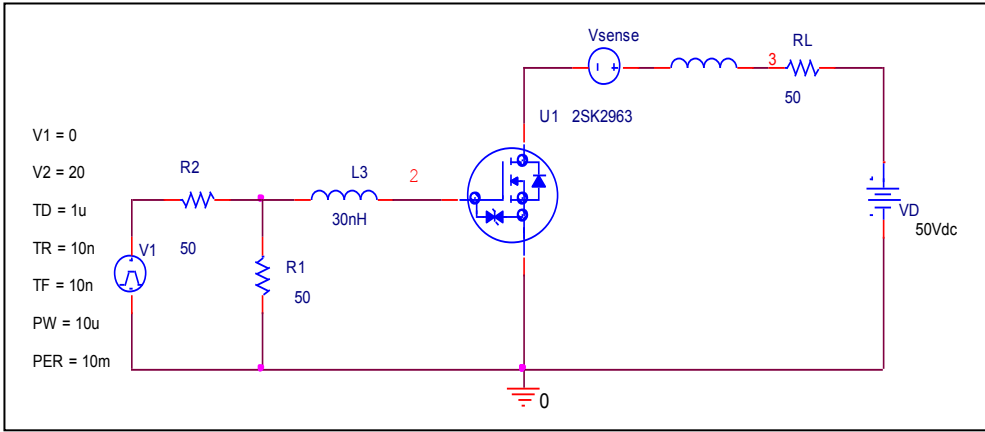
V _{Ds} (V)	Cbd(pF)		Error(%)
	Measurement	Simulation	
1	65.0000	64.9020	-0.1508
2	50.0000	50.2170	0.4340
5	35.0000	34.6660	-0.9543
10	26.0000	25.9100	-0.3462
20	19.0000	19.2520	1.3263
50	12.5000	12.9170	3.3360
100	10.0000	9.6640	-3.3600

Switching Time Characteristic

Circuit Simulation result



Evaluation circuit

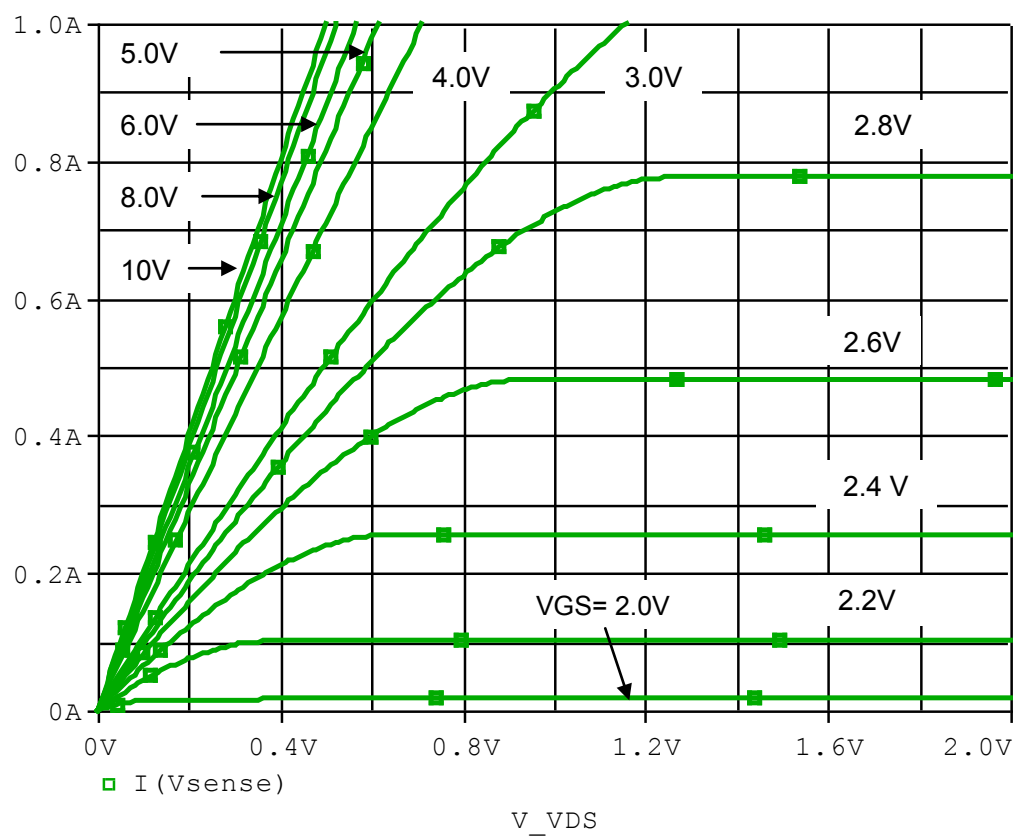


Simulation Result

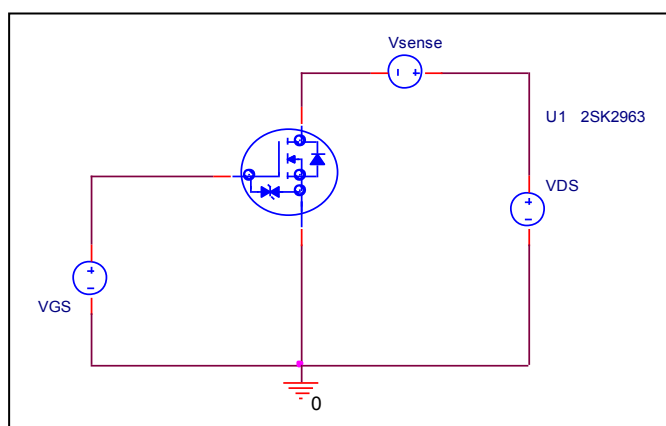
$I_D=1A$, $V_{DD}=80V$, $V_{GS}=0/10V$	Measurement		Simulation		Error(%)
Td(on)	13.000	ns	13.071	ns	0.5462

Output Characteristic

Circuit Simulation result

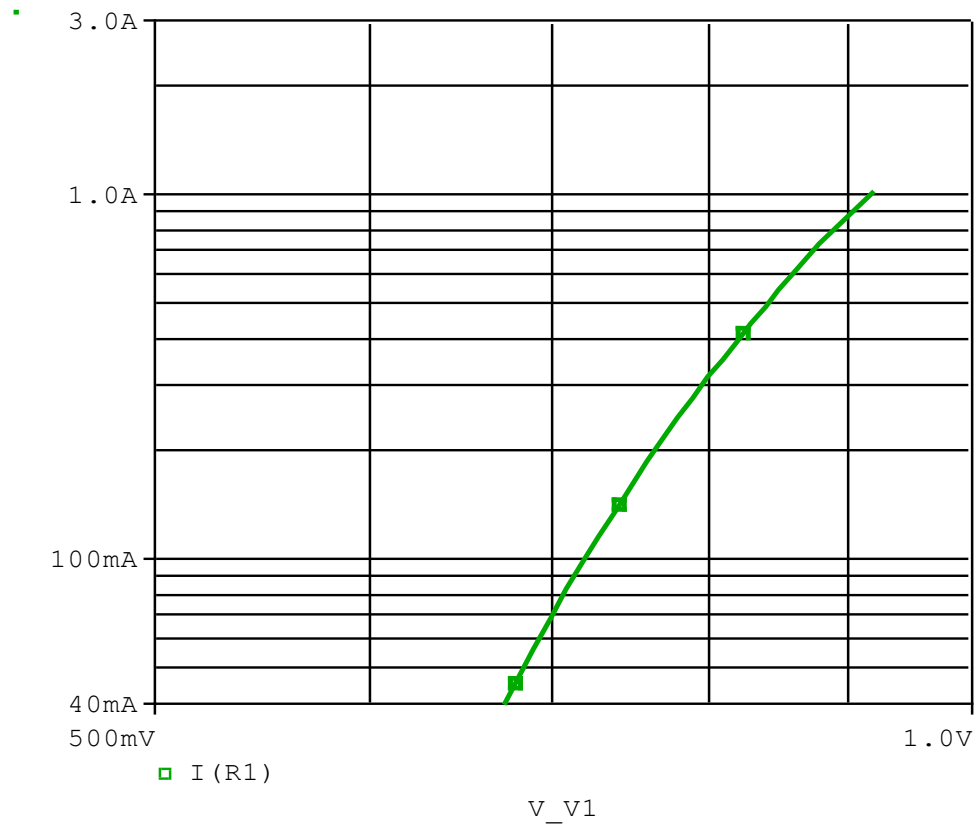


Evaluation circuit

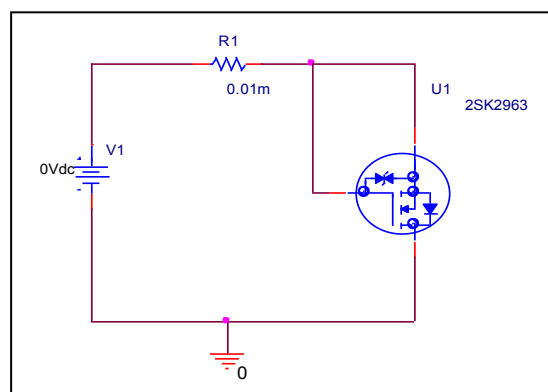


BODY DIODE SPICE MODEL Forward Current Characteristic

Circuit Simulation Result

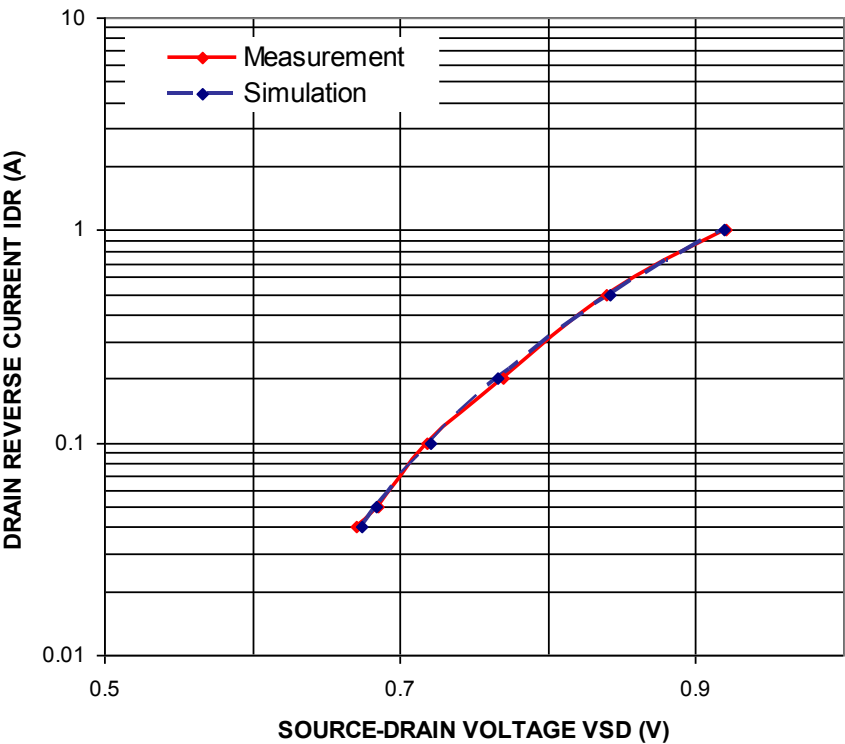


Evaluation Circuit



Comparison Graph

Circuit Simulation Result

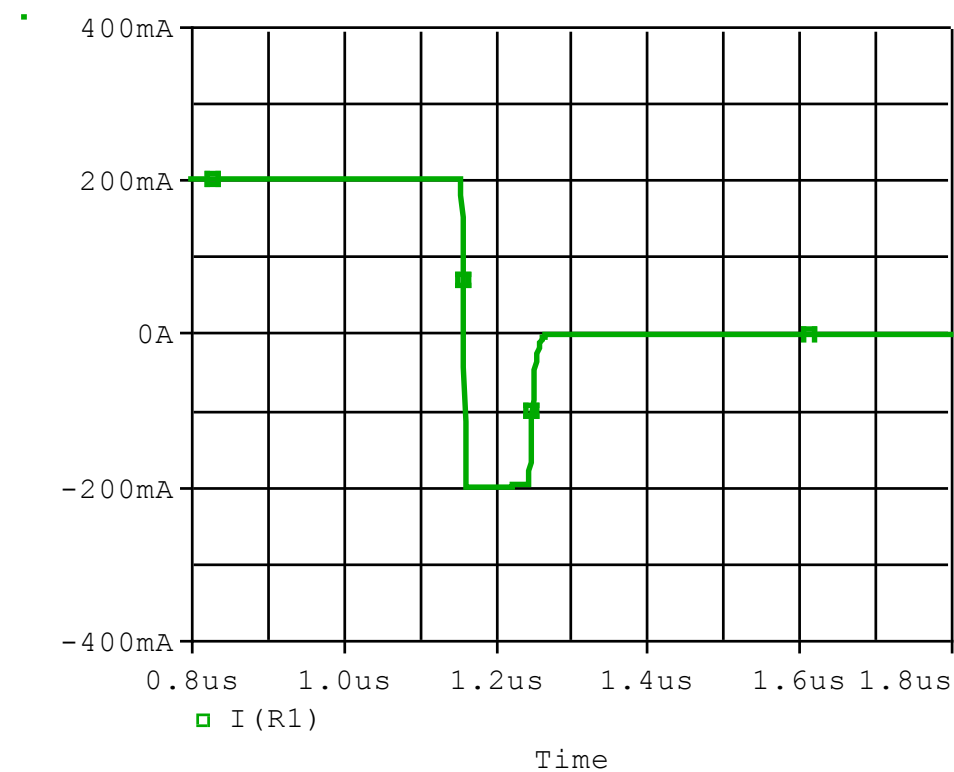


Simulation Result

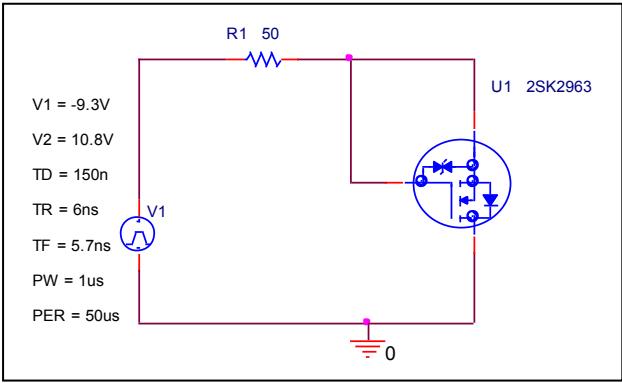
IDR(A)	VSD(V)		%Error
	Measurement	Simulation	
0.04	0.6700	0.6742	0.6203
0.05	0.6850	0.6844	-0.0835
0.1	0.7180	0.7209	0.4040
0.2	0.7700	0.7660	-0.5182
0.5	0.8400	0.8416	0.1848
1	0.9200	0.9196	-0.0418

Reverse Recovery Characteristic (Body Diode)

Circuit Simulation Result



Evaluation Circuit

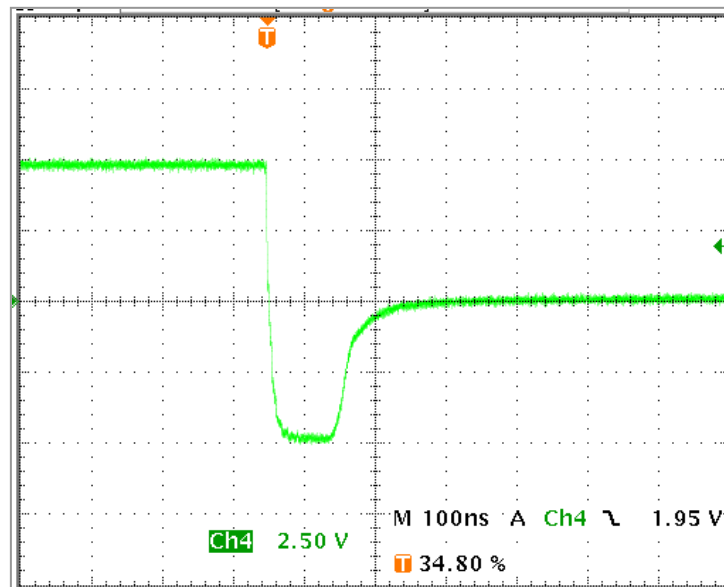


Compare Measurement vs. Simulation

	Measurement		Simulation		Error (%)
trj	86.000	ns	86.062	ns	0.0720

Reverse Recovery Characteristic (Body Diode)

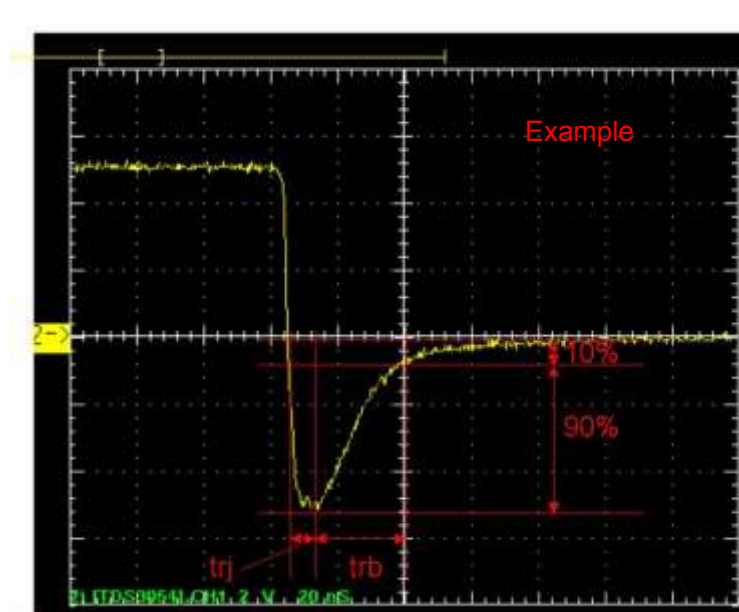
Reference



$T_{rj} = (86\text{ns})$

$T_{rb} = (64\text{ns})$

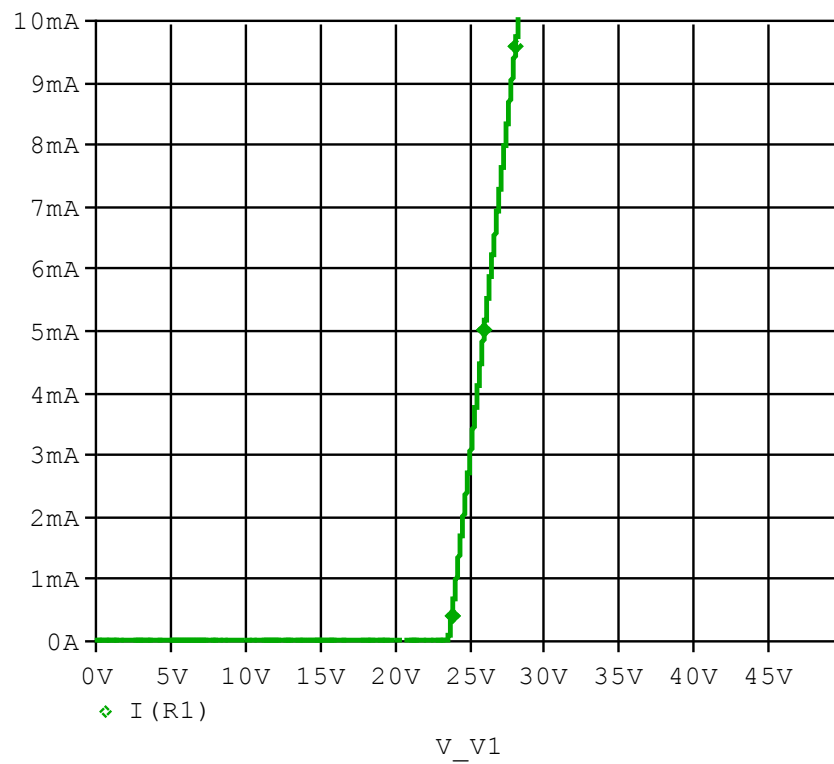
Conditions: $I_{fwd} = 0.2$, $I_{rev} = 0.2(\text{A})$, $R_I = 50$



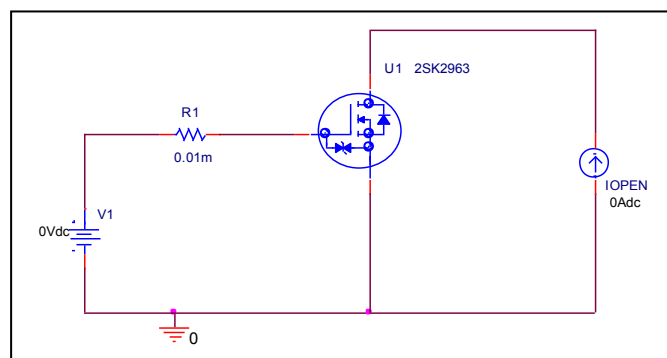
Relation between t_{rj} and t_{rb}

Zener Voltage Characteristic

Circuit Simulation Result



Evaluation Circuit



Zener Voltage Characteristic

Reference

